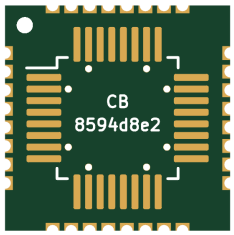
Chip-Bridge Technologies

CB 8594D8E2

Host: 32-TQFP 7 x 7mm — Guest: 32-LQFP 5 x 5mm



Adapter Interfaces

Table 1: Adapter Parameters

Parameter	Host	Guest	Unit
Package	TQFP	LQFP	-
Pin Count	32	32	-
Package Dim.	7 x 7	5 x 5	mm
Pitch	0.8	0.5	mm

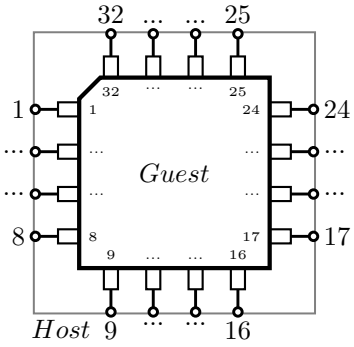


Figure 1: Adapter Pinout

Features

- Drop-in adapter; Install 32-LQFP 5 x 5mm on a 32-TQFP 7 x 7mm footprint
- Low profile adapter, 0.8mm
- Supports common manufacturing methods
- 1:1 Pinout Configuration

Host Pins	Guest Pins
1	1
2	2
3	3
4	4
...	...
29	29
30	30
31	31
32	32

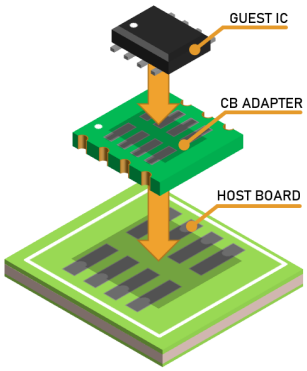
Table 2: Pin Configuration

General Description

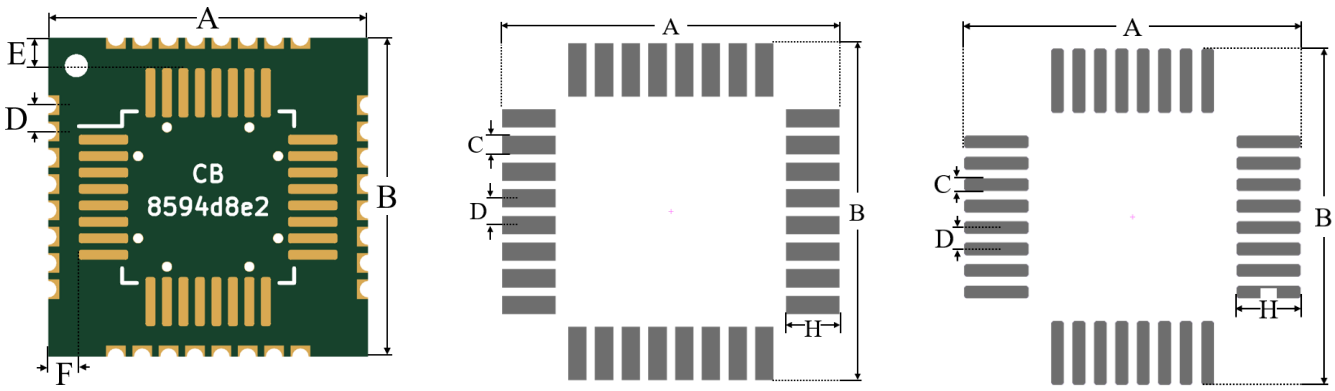
This device is a drop-in footprint to footprint adapter for your existing PBC design. Each Chip-Bridge Technologies adapter is designed to fit on the stated **Host Footprint**, and provide a **Guest Footprint** with electrical connections for your replacement IC.

Visit chipbridgetech.com/products to find our full product catalog. If you have questions or would like to request a design specific to your application, please contact our support team at support@chipbridgetech.com.

Chip-Bridge Technologies Adapaters are a patent pending design.



Mechanical Specifications



(a) Adapter Diagram (b) Host Footprint (c) Guest Footprint

Figure 2: Mechanical Outline

Print version not to scale.

Table 3: Mechanical Specification

	Units	A	B	C	D	E	F	G	H	I
Adapter[1]	mm	9.7 ± 0.127	9.7 ± 0.127	-	0.8	0.925	0.925	-	-	-
Host Footprint[1,2]	mm	1.10	1.10	0.55	0.8	-	-	-	1.6	-
Guest Footprint[1,3]	mm	7.85	7.85	0.3	0.5	-	-	-	-	-

[1] Tolerances ±0.1mm unless otherwise stated.
[2] Host IC Reference Drawing: microchip.com/downloads/en/PackagingSpec/00000049BS.pdf
[3] Guest IC Reference Drawing: nxp.com/docs/en/package-information/SOT401-1.pdf

Trace Specifications

Table 4: Adapter Trace Specifications

Parameter	Symbol	Min.	Typ.	Max.	Unit	Conditions
Trace Resistance	R_{trace}[4]	0.1	2.7	15.0	mΩ	20°C
Trace to Trace Clearance	$d_{clearance}$		150 ± 13		µm	

[4] Calculated values.

Datasheet Updates

The information in this document is subject to change without notice.